PH3230S

N-channel TrenchMOS intermediate level FET

Rev. 04 — 27 November 2009 Product data sheet

1. Product profile

1.1 General description

Intermediate level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product is designed and qualified for use in computing, communications, consumer and industrial applications only.

1.2 Features and benefits

- Low conduction losses due to low on-state resistance
- Saves PCB space due to small footprint
- Simple gate drive required due to low gate charge
- Suitable for logic level gate drive sources

1.3 Applications

- Computer motherboards
- DC-to-DC convertors
- Notebook computers
- Switched-mode power supplies

1.4 Quick reference data

Table 1. Quick reference

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 150$ °C	-	-	30	V
I_D	drain current	$T_{mb} = 25$ °C; $V_{GS} = 10$ V; see Figure 1 and 3	-	-	100	A
P_{tot}	total power dissipation	$T_{mb} = 25$ °C; see Figure 2	-	-	62.5	W
Dynamic characteristics						
Q_{GD}	gate-drain charge	$V_{GS} = 5$ V; $I_D = 50$ A; $V_{DS} = 10$ V; $T_j = 25$ °C; see Figure 12	-	13	-	nC
Static characteristics						
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10$ V; $I_D = 25$ A; $T_j = 25$ °C; see Figure 9 and 10	-	2.7	3.2	mΩ

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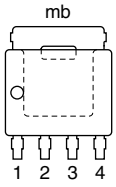
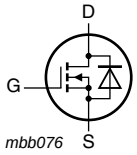
2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

SOT669 (LFPAK)

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PH3230S	LFPAK	plastic single-ended surface-mounted package (LFPAK); 4 leads	SOT669

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 150$ °C	-	30	V
V_{GS}	gate-source voltage		-20	20	V
I_D	drain current	V_{GS} = 10 V; T_{mb} = 25 °C; see Figure 1 and 3	-	100	A
		V_{GS} = 10 V; T_{mb} = 100 °C; see Figure 1	-	63	A
I_{DM}	peak drain current	$t_p \leq 10$ µs; pulsed; T_{mb} = 25 °C; see Figure 3	-	300	A
P_{tot}	total power dissipation	T_{mb} = 25 °C; see Figure 2	-	62.5	W
T_{stg}	storage temperature		-55	150	°C
T_j	junction temperature		-55	150	°C
Source-drain diode					
I_S	source current	T_{mb} = 25 °C	-	52	A
I_{SM}	peak source current	$t_p \leq 10$ µs; pulsed; T_{mb} = 25 °C	-	156	A
Avalanche ruggedness					
$E_{DS(AL)R}$	repetitive drain-source avalanche energy	V_{GS} = 10 V; I_D = 5 A; V_{sup} = 15 V; $R_{GS} \geq 50$ Ω	-	2.5	mJ
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; I_D = 50 A; $V_{sup} \leq 15$ V; unclamped; R_{GS} = 50 Ω	-	250	mJ

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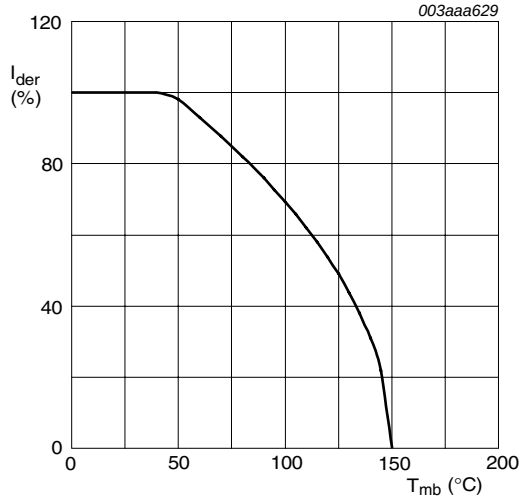
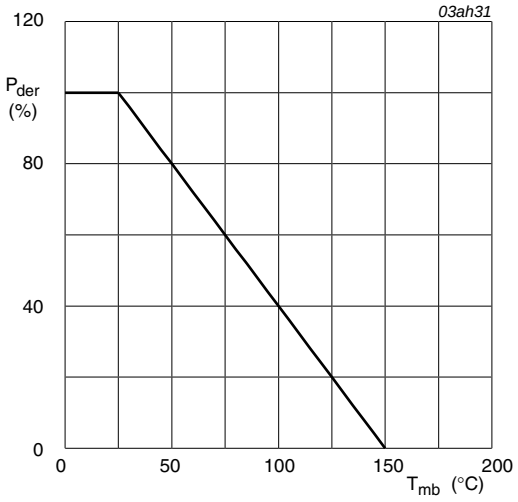


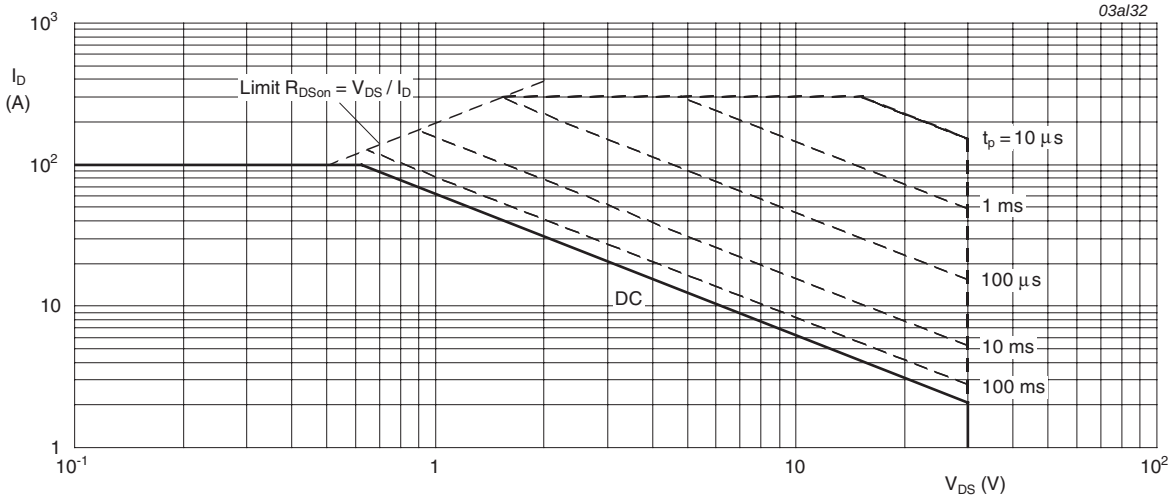
$$V_{GS} \geq 10V I_{der} = \frac{I_D}{I_{D(25°C)}} \times 100\,\%$$

Fig 1. Normalized continuous drain current as a function of mounting base temperature



$$P_{der} = \frac{P(tot)}{P_{tot(25°C)}} \times 100\,\%$$

Fig 2. Normalized total power dissipation as a function of mounting base temperature



$$T_{mb} = 25°C; I_{DM} \text{ is single pulse}$$

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

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5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j\text{-}mb)}$	thermal resistance from junction to mounting base	see Figure 4	-	-	2	K/W

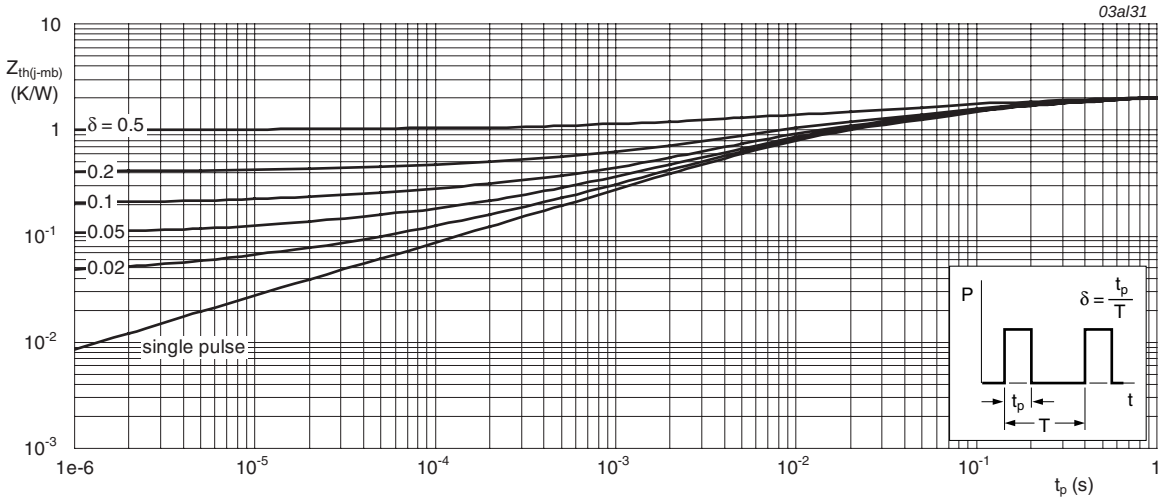

Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

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6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = 10 mA; V_{GS} = 0 V; T_j = 25 °C	30	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	I_D = 1 mA; V_{DS}= V_{GS}; T_j = 25 °C; see Figure 8	1	2	3	V
I_{DSS}	drain leakage current	V_{DS} = 30 V; V_{GS} = 0 V; T_j = 25 °C	-	-	1	µA
I_{GSS}	gate leakage current	V_{GS} = 20 V; V_{DS} = 0 V; T_j = 25 °C	-	10	100	nA
		V_{GS} = -20 V; V_{DS} = 0 V; T_j = 25 °C	-	10	100	nA
R_{DSon}	drain-source on-state resistance	V_{GS} = 4.5 V; I_D = 25 A; T_j = 25 °C; see Figure 9	-	5	6.5	mΩ
		V_{GS} = 10 V; I_D = 25 A; T_j = 25 °C; see Figure 9 and 10	-	2.7	3.2	mΩ
Source-drain diode						
V_{SD}	source-drain voltage	I_S = 25 A; V_{GS} = 0 V; T_j = 25 °C; see Figure 11	-	0.8	1.2	V
t_{rr}	reverse recovery time	I_S = 20 A; dI_S/dt = -50 A/µs; V_{GS} = 0 V; V_{DS} = 25 V; T_j = 25 °C	-	46	-	ns
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	I_D = 50 A; V_{DS} = 10 V; V_{GS} = 5 V; T_j = 25 °C; see Figure 12	-	42	-	nC
Q_{GS}	gate-source charge		-	21	-	nC
Q_{GD}	gate-drain charge		-	13	-	nC
C_{iss}	input capacitance	V_{DS} = 10 V; V_{GS} = 0 V; f = 1 MHz; T_j = 25 °C; see Figure 13	-	4100	-	pF
C_{oss}	output capacitance		-	1150	-	pF
C_{rss}	reverse transfer capacitance		-	750	-	pF
$t_{d(on)}$	turn-on delay time	V_{DS} = 10 V; R_L = 0.4 Ω; V_{GS} = 10 V; $R_{G(ext)}$ = 4.7 Ω; T_j = 25 °C	-	14	-	ns
t_r	rise time		-	37	-	ns
$t_{d(off)}$	turn-off delay time		-	85	-	ns
t_f	fall time		-	37	-	ns
g_{fs}	transfer conductance	V_{DS} = 10 V; I_D = 25 A; T_j = 25 °C; see Figure 14	39	75	-	S

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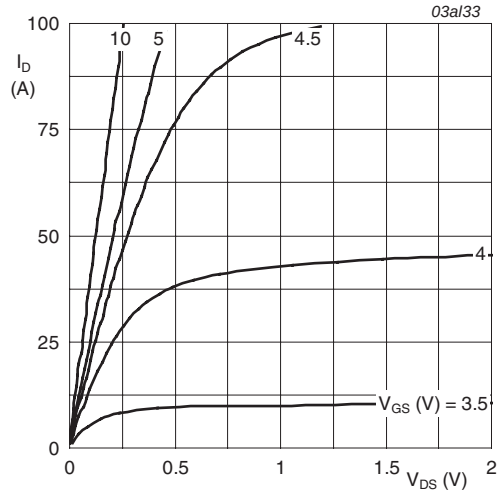
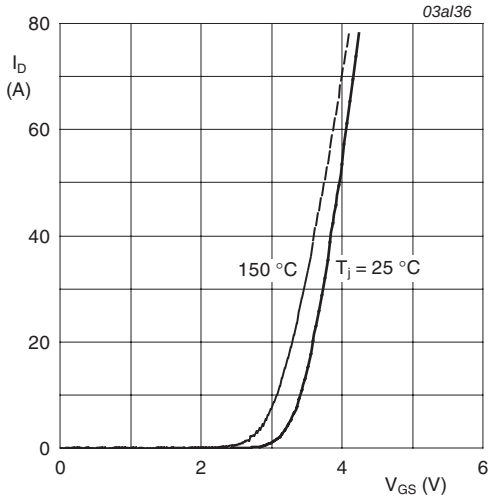


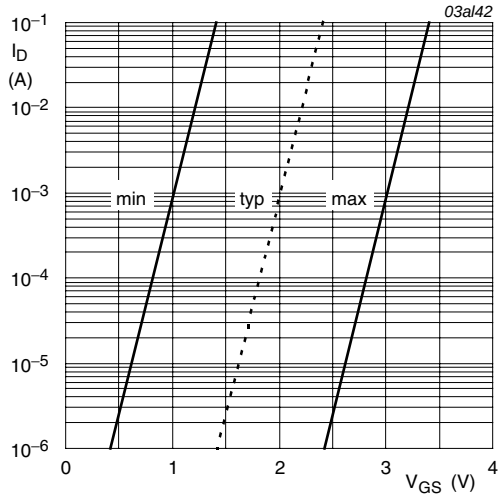
$T_j = 25°C$

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values



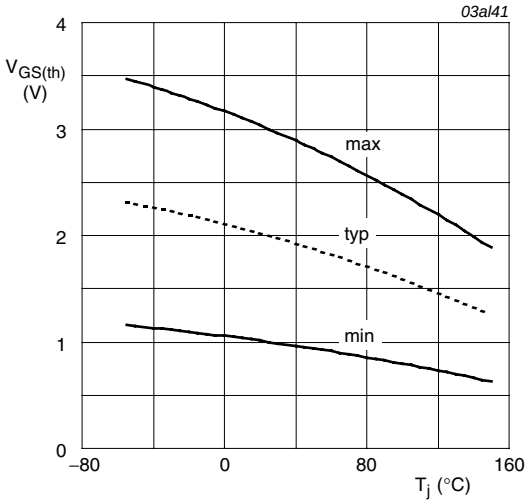
$T_j = 25°C \text{ and } 150°C; V_{DS} > I_D \times R_{DSon}$

Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values



$T_j = 25°C$

Fig 7. Sub-threshold drain current as a function of gate-source voltage



$I_D = 1mA; V_{DS} = V_{GS}$

Fig 8. Gate-source threshold voltage as a function of junction temperature

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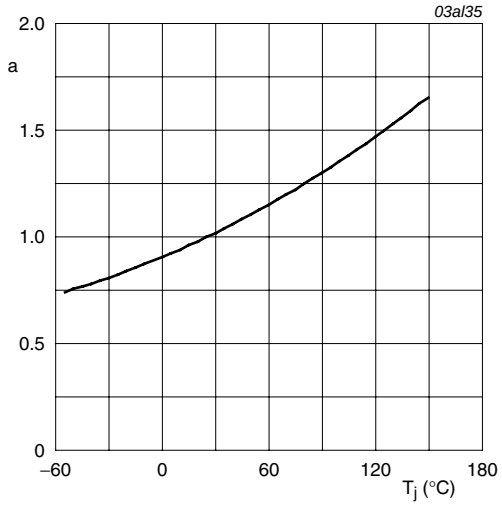
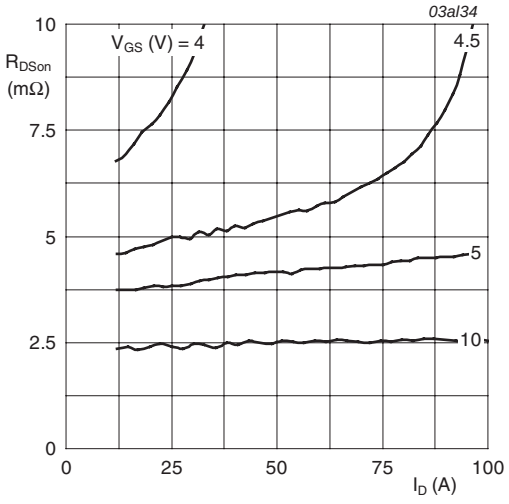


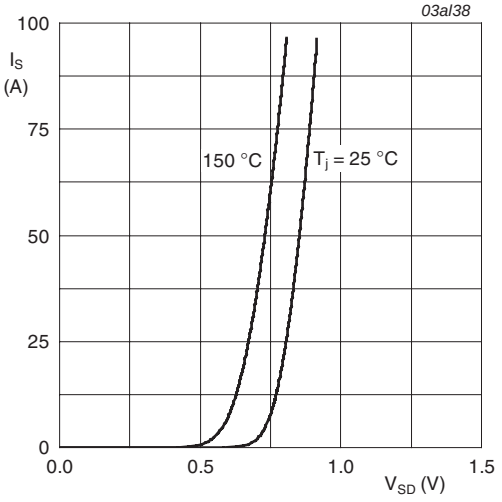
$$a = \frac{R_{DSon}}{R_{DSon(25°C)}}$$

Fig 9. Normalized drain-source on-state resistance factor as a function of junction temperature



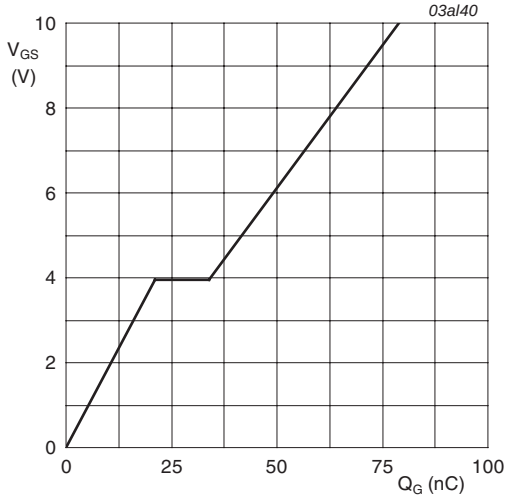
$$T_j = 25°C$$

Fig 10. Drain-source on-state resistance as a function of drain current; typical values



$$T_j = 25°C \text{ and } 150°C; V_{GS} = 0V$$

Fig 11. Source current as a function of source-drain voltage; typical values



$$T_j = 25°C; I_D = 50A; V_{DD} = 10V$$

Fig 12. Gate-source voltage as a function of gate charge; typical values

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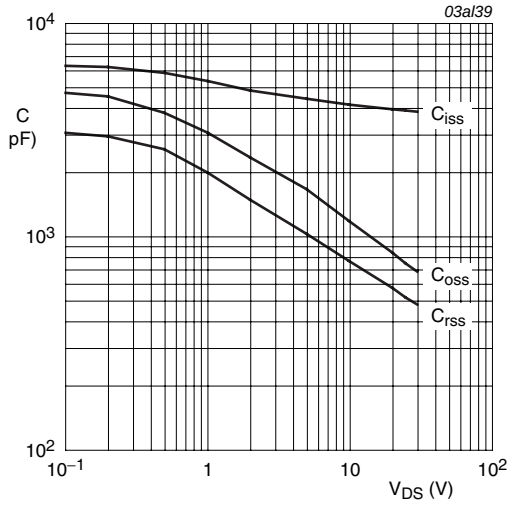
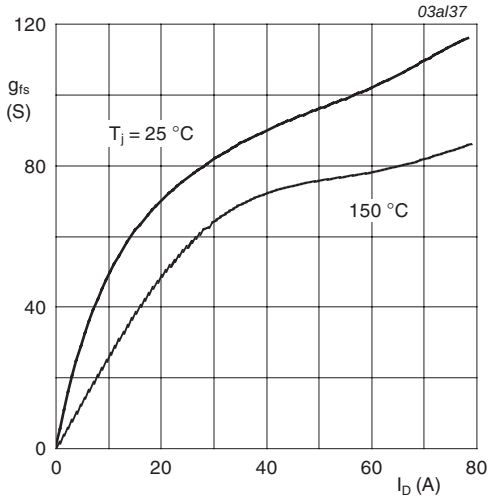


$V_{GS} = 0V; f = 1MHz$

Fig 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$T_j = 25°C \text{ and } 150°C; V_{DS} > I_D \times R_{DSon}$

Fig 14. Forward transconductance as a function of drain current; typical values

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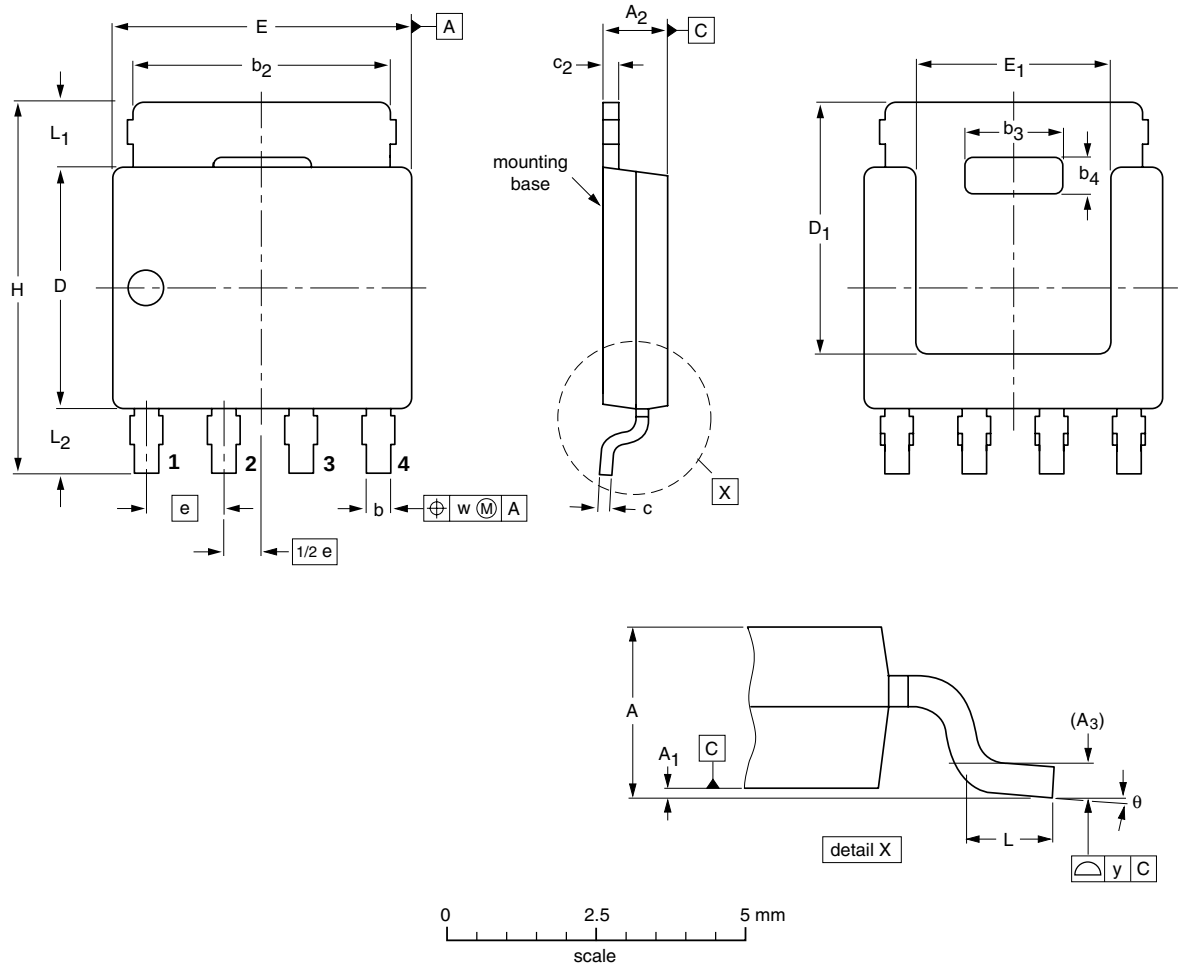
7. Package outline

Plastic single-ended surface-mounted package (LFPAK); 4 leads **SOT669**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	A_2	A_3	b	b_2	b_3	b_4	c	c_2	$D^{(1)}$	$D_1^{(1)}$ max	$E^{(1)}$	$E_1^{(1)}$	e	H	L	L_1	L_2	w	y	θ
mm	1.20 1.01	0.15 0.00	1.10 0.95	0.25	0.50 0.35	4.41 3.62	2.2 2.0	0.9 0.7	0.25 0.19	0.30 0.24	4.10 3.80	4.20	5.0 4.8	3.3 3.1	1.27	6.2 5.8	0.85 0.40	1.3 0.8	1.3 0.8	0.25	0.1	8° 0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT669		MO-235				~~04-10-13~~ 06-03-16

Fig 15. Package outline SOT669 (LFPAK)

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8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PH3230S_4	20091127	Product data sheet	-	PH3230S-03
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate.			
PH3230S-03 (9397 750 12756)	20040302	Product data	-	PH3230S-02
PH3230S-02 (9397 750 11279)	20030423	Product data	-	PH3230S-01
PH3230S-01 (9397 750 11078)	20030212	Preliminary data	-	-

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9. Legal information

9.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URLhttp://www.nxp.com.

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11. Contents

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Date of release: 27 November 2009
Document identifier: PH3230S_4

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